

## ABSTRACT

A method and a system for jetting droplets of  
5 viscous medium, such as solder paste, onto a substrate,  
such as an electronic circuit board. The volume of the  
droplets are adjusted by regulating the amount of viscous  
medium that is fed into a jetting nozzle for subsequent  
jetting of the viscous medium droplets therefrom. The  
10 exit velocity of the jetted droplets is adjusted or  
maintained substantially constant by regulating the  
velocity with which the viscous medium is impacted.  
Furthermore, the rate at which viscous medium is fed, for  
instance by a feed screw, into the nozzle is adjusted in  
15 order to regulate the feeding time required for feeding  
the viscous medium into the jetting nozzle, for instance  
in order to maintain a constant feeding time.

20 Fig. 1